

Super low hardness (ASKER C 8) Thermal Pad

Features

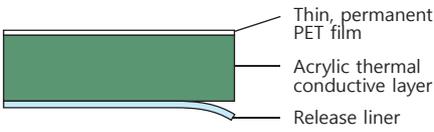
- 2W/m•K and compilable (ASKER C 8) allows for less pressure on the heat source, such as the IC or PCB.
- Allows for lower thermal resistance on an uneven surfaces.
- Silicone-free material – no siloxane outgassing.

(The values below are not guaranteed.)

Test type	Unit	Standard	CPSS-F	CPSS
Thermal Conductivity	W/m•K	JIS R 2616 (Hot-wire method)	2.0	2.0
		ISO22007-2 (Hot Disc method)	1.4	1.4
Color	—	—	Darkgreen	Darkgreen
Thickness	mm	—	1.0 / 1.5 / 2.0 2.5 / 3.0 / 4.0	3.0 / 4.0
Specific Gravity	—	JIS Z 8807	1.92	1.92
Hardness	ASKER C	JIS K 7312	8	8
	Shore 00	ASTM D 2240	33	33
Tensile strength	MPa	JIS K 6251	0.28	—
Elongation rate	%	JIS K 6251	8.9	—
Volume Resistivity	Ω•cm	JIS K 6911 compliant	1.0×10 ¹²	1.0×10 ¹²
Breakdown voltage	kV/mm	JIS C 2110-1 compliant	3.5	—
Withstanding voltage	kV/mm	JIS C 2110-1 compliant	2.8	—
Tracking resistance	—	JIS C 2134	600≤CTI (t=4.0mm)	600≤CTI (t=4.0mm)
Dielectric constant	1MHz	Company standard	14.6	—
Loss tangent	1MHz	Company standard	0.09	—
Flammability	—	UL94	V-2 (t1.0 - 3.0mm)	—
			V-0 (t4.0mm)	—
Operating temp	°C	—	-40 ~ 100	-40 ~ 100
Available max. dimension ^{※1)}	mm	—	200×500	200×500

※1) For usable dimensions, custom cuts, and material yield, contact your local sales department.

One-side tacky type / CPSS-F



Both-side tacky type / CPSS

